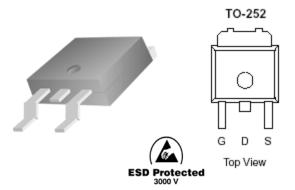
N-Channel 40-V (D-S) MOSFET

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low $r_{DS(on)}$ and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

V _{DS} (V)	$r_{DS(on)} m(\Omega)$	I _D (A)
40	$32 @ V_{GS} = 10V$	33
40	$42 @ V_{GS} = 4.5V$	29

- Low $r_{DS(on)}$ provides higher efficiency and extends battery life
- Low thermal impedance copper leadframe DPAK saves board space
- Fast switching speed
- High performance trench technology



PRODUCT SUMMARY

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C UNLESS OTHERWISE NOTED)					
Parameter			Limit	Units	
Drain-Source Voltage		V_{DS}	40	V	
Gate-Source Voltage	V_{GS}	±20			
Continuous Drain Current ^a	$T_C=25^{\circ}C$	I_D	33	A	
Pulsed Drain Current ^b		I_{DM}	40	A	
Continuous Source Current (Diode Conduction) ^a			30	A	
Power Dissipation ^a	$T_C=25^{\circ}C$	P_{D}	50.0	W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Maximum	Units		
Maximum Junction-to-Ambient ^a	$R_{ heta JA}$	50	°C/W		
Maximum Junction-to-Case	$R_{ heta JC}$	3.0	°C/W		

1

Notes

- a. Surface Mounted on 1" x 1" FR4 Board.
- b. Pulse width limited by maximum junction temperature

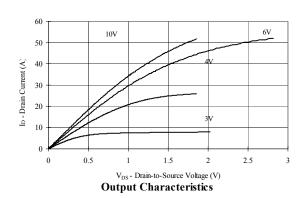
Parameter	Symbol	Test Conditions	Limits			Unit	
r ar ameter	Symbol Test Conditions		Min	Тур	Max	Umit	
Static							
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \text{ uA}$	1			V	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = 20 \text{ V}$			±100	nA	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55^{\circ}\text{C}$			25	uA	
On-State Drain Current ^A	I _{D(on)}	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	34		23	A	
Drain-Source On-Resistance ^A	r _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 33 \text{ A}$ $V_{GS} = 4.5 \text{ V}, I_D = 29 \text{ A}$			32 42	mΩ	
Forward Tranconductance ^A	g_{fs}	$V_{DS} = 15 \text{ V}, I_D = 33 \text{ A}$		22		S	
Diode Forward Voltage	V_{SD}	$I_S = 34 \text{ A}, V_{GS} = 0 \text{ V}$		1.1		V	
Pulsed Source Current (Body Diode) ^A	I_{SM}			5		A	
Dynamic ^b							
Total Gate Charge	Q_{g}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V},$		5			
Gate-Source Charge	Q_{gs}	$I_{DS} = 13 \text{ V}, \text{ V}_{GS} = 4.3 \text{ V},$ $I_{D} = 33 \text{ A}$		1.1		nC	
Gate-Drain Charge	Q_{gd}	тр 3371		1.4			
Input Capacitance	C_{iss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$		489		рF	
Output Capacitance	C_{oss}	f = 1MHz		94		PI.	
Turn-On Delay Time	$t_{d(on)}$			16			
Rise Time	$t_{\rm r}$	$V_{DD} = 25 \text{ V}, R_L = 25 \Omega, I_D = 34 \text{ A},$		5		nS	
Turn-Off Delay Time	$t_{d(off)}$	$V_{GEN} = 10 V$		23			
Fall-Time	t_{f}			3			

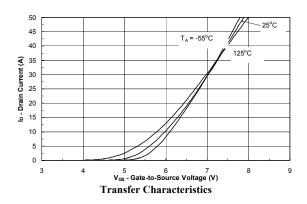
Notes

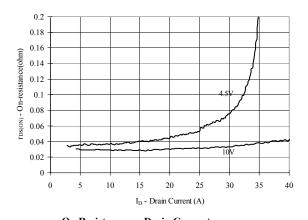
- a. Pulse test: $PW \le 300us duty cycle \le 2\%$.
- b. Guaranteed by design, not subject to production testing.

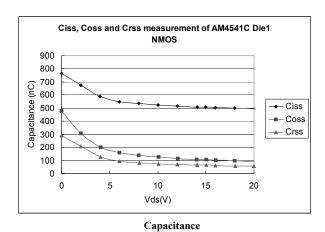
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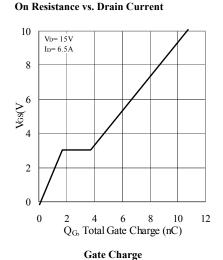
Typical Electrical Characteristics

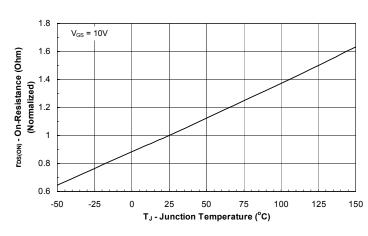






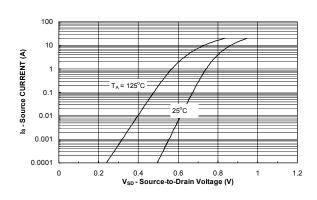


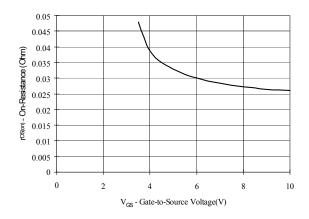




On-Resistance vs. Junction Temperature

Typical Electrical Characteristics

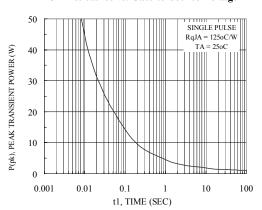




Source-Drain Diode Forward Voltage

4.7 4.5 4.3 8 4.1 9 3.9 3.7 3.7 3.1 2.9 2.7 -50 -25 0 25 50 75 100 125 150 T_J - Temperature (°C)

On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

Figure 10. Single Pulse Maximum Power Dissipation



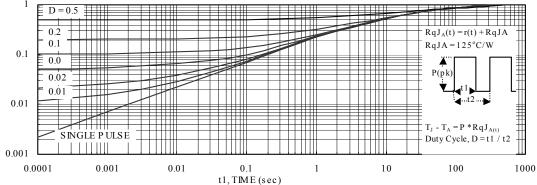
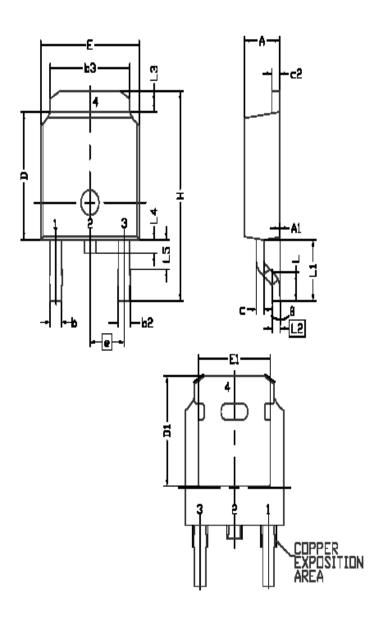


Figure 11. Transient Thermal Response Curve

Package Information



CHADE	DIMENS:	iinal i	REGMTS		
LOGMY2	MIN	Ž	MAX		
Ε	6.40	6.60	6,731		
L	1.40	1.52	1.77		
L1	2.743 REF				
L2		.508 BS	ñ		
L3	0.89	1	1.27		
L4	0.64		턤		
15	1	ı	-		
D	6.00	6.10	6'553		
H	9.40	10,00	10.40		
٩	0.64	0.76	0.88		
P5	0.77	0.84	1.14		
ь3	5.21	5.34	5.46		
٠		286 BS	3		
A	2.20	2.30	5'38		
A1	0		0.127		
u	0.45	0.50	0.60		
-52	0.45	0.50	0.58		
М	5.30		-		
c	4.40		I		
8	ò	1	10*		